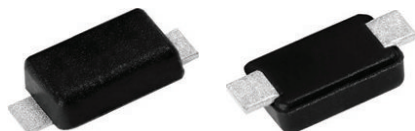


# Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier

## eSMP® Series



Top view

Bottom view

### SMF (DO-219AB)

Cathode  Anode

**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## FEATURES

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available  
- Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

## LINKS TO ADDITIONAL RESOURCES



## PRIMARY CHARACTERISTICS

|                                        |                |
|----------------------------------------|----------------|
| $I_{F(AV)}$                            | 2.0 A          |
| $V_{RRM}$                              | 200 V          |
| $I_{FSM}$                              | 60 A           |
| $V_F$ at $I_F = 2$ A ( $T_A = 125$ °C) | 0.64 V         |
| $T_J$ max.                             | 175 °C         |
| Package                                | SMF (DO-219AB) |
| Circuit configuration                  | Single         |

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

**Case:** SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3\_X - halogen-free, RoHS-compliant, and AEC-Q101 qualified

("\_X" denotes revision code e.g. A, B,.....)

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

## MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

| PARAMETER                                                                          | SYMBOL                     | V2F22       | UNIT |
|------------------------------------------------------------------------------------|----------------------------|-------------|------|
| Device marking code                                                                |                            | V2D         |      |
| Maximum repetitive peak reverse voltage                                            | $V_{RRM}$                  | 200         | V    |
| Maximum DC reverse voltage                                                         | $V_{DC}$                   | 160         | V    |
| Maximum average forward rectified current (fig.1)                                  | $I_{F(AV)}$ <sup>(1)</sup> | 2.0         | A    |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$                  | 60          | A    |
| Operating junction temperature range                                               | $T_J$ <sup>(2)</sup>       | -40 to +175 | °C   |
| Storage temperature range                                                          | $T_{STG}$                  | -55 to +175 |      |

### Notes

<sup>(1)</sup> Free air, mounted on recommended copper pad area

<sup>(2)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



| ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted) |                        |                         |                               |      |      |      |
|----------------------------------------------------------------------------|------------------------|-------------------------|-------------------------------|------|------|------|
| PARAMETER                                                                  | TEST CONDITIONS        |                         | SYMBOL                        | TYP. | MAX. | UNIT |
| Instantaneous forward voltage                                              | I <sub>F</sub> = 1.0 A | T <sub>A</sub> = 25 °C  | V <sub>F</sub> <sup>(1)</sup> | 0.72 | -    | V    |
|                                                                            | I <sub>F</sub> = 2.0 A |                         |                               | 0.79 | 0.87 |      |
|                                                                            | I <sub>F</sub> = 1.0 A | T <sub>A</sub> = 125 °C |                               | 0.56 | -    |      |
|                                                                            | I <sub>F</sub> = 2.0 A |                         |                               | 0.64 | 0.72 |      |
| Reverse current                                                            | V <sub>R</sub> = 160 V | T <sub>A</sub> = 25 °C  | I <sub>R</sub> <sup>(2)</sup> | 0.3  | -    | μA   |
|                                                                            |                        | T <sub>A</sub> = 125 °C |                               | 300  | -    |      |
|                                                                            | V <sub>R</sub> = 200 V | T <sub>A</sub> = 25 °C  |                               | -    | 60   |      |
|                                                                            |                        | T <sub>A</sub> = 125 °C |                               | 700  | 3500 |      |
| Typical junction capacitance                                               | 4.0 V, 1 MHz           |                         | C <sub>J</sub>                | 160  | -    | pF   |

**Notes**

- (1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle  
 (2) Pulse test: Pulse width  $\leq 5\text{ ms}$

| THERMAL CHARACTERISTICS ( $T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted) |                          |       |                      |
|--------------------------------------------------------------------------------------|--------------------------|-------|----------------------|
| PARAMETER                                                                            | SYMBOL                   | V2F22 | UNIT                 |
| Typical thermal resistance                                                           | $R_{\theta JA}^{(1)(2)}$ | 125   | $^{\circ}\text{C/W}$ |
|                                                                                      | $R_{\theta JM}^{(3)}$    | 26    |                      |

**Notes**

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$   
 (2) Free air, mounted on recommended copper pad area; thermal resistance  $R_{\theta JA}$  - junction to ambient  
 (3) Mounted on recommended copper pad area; thermal resistance  $R_{\theta JM}$  - junction to mount

| ORDERING INFORMATION (Example) |                 |                        |               |                                    |
|--------------------------------|-----------------|------------------------|---------------|------------------------------------|
| PREFERRED P/N                  | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
| V2F22-M3/H                     | 0.015           | H                      | 3000          | 7" diameter plastic tape and reel  |
| V2F22-M3/I                     | 0.015           | I                      | 10 000        | 13" diameter plastic tape and reel |
| V2F22HM3_A/H <sup>(1)</sup>    | 0.015           | H                      | 3000          | 7" diameter plastic tape and reel  |
| V2F22HM3_A/I <sup>(1)</sup>    | 0.015           | I                      | 10 000        | 13" diameter plastic tape and reel |

**Note**

- (1) AEC-Q101 qualified

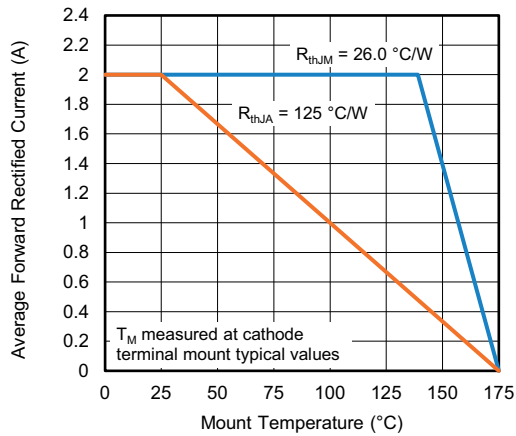
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

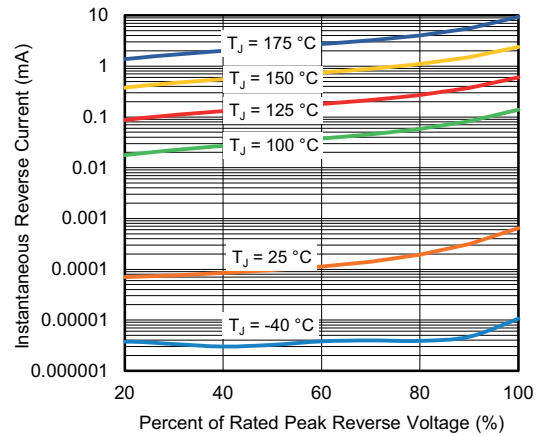


Fig. 4 - Typical Reverse Leakage Characteristics

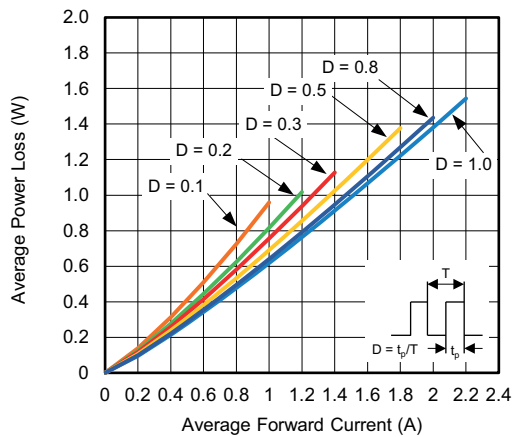


Fig. 2 - Average Power Loss Characteristics

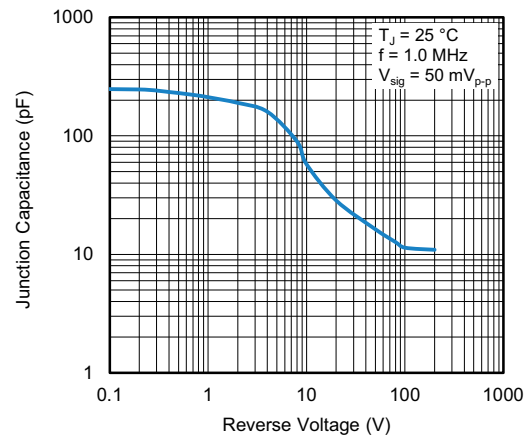


Fig. 5 - Typical Junction Capacitance

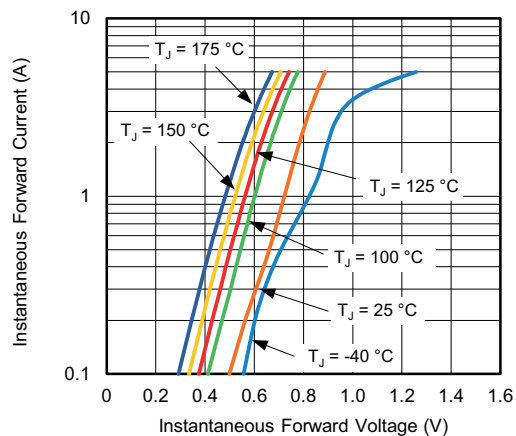


Fig. 3 - Typical Instantaneous Forward Characteristics

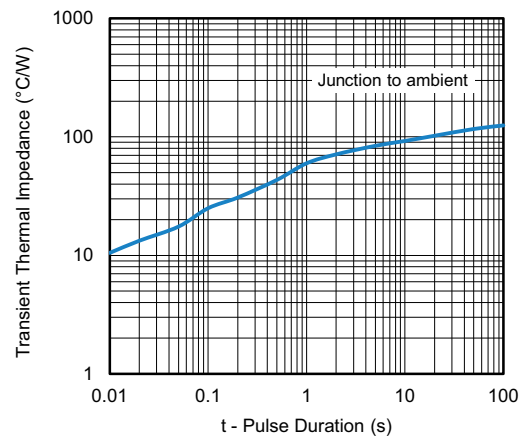
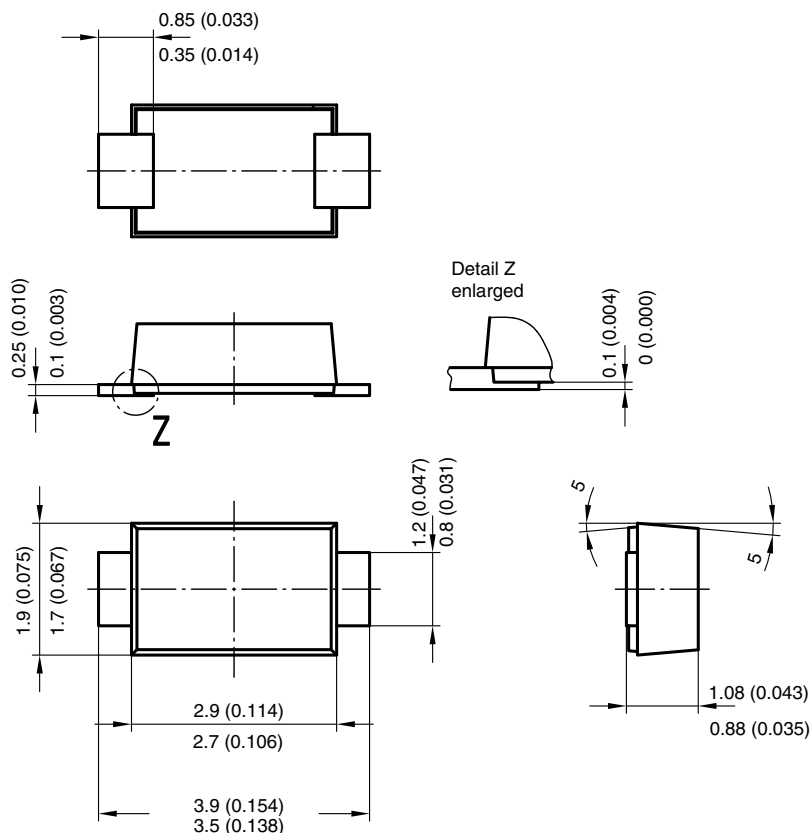
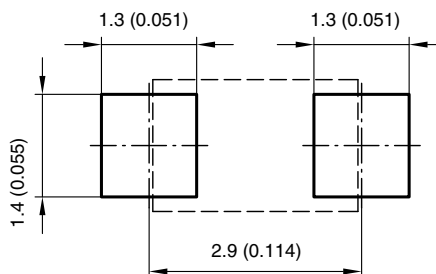


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in millimeters (inches)


Foot print recommendation:



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